# Instructions to Prepare a One Page Abstract for theV International Conference on Simulation for Additive Manufacturing (Sim-AM 2025)

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ABSTRACT

People interested in submitting a contribution to **SIM-AM 2025** are requested to submit electronically a one-page abstract no later than **April 7, 2025**. Abstracts should briefly outline the main features, results and conclusions as well as their general significance, and contain relevant references.

The abstract must be converted to Portable Document Format (PDF) before submission through the Conference web site.

The abstract has to be written in English with Times-Roman letters. The number of lines of the abstract body should not exceed 300 words.

The abstract must contain the full name and full address of author/s. In the case of joint authorships, the name of the author who will actually present the paper at the Congress should be indicated with an asterisk. Abstracts can only be accepted on the understanding that the work will be presented in person at the Conference.

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**REFERENCES**

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[2] J.A. Turner, J. Belak, et.al, ExaAM: Metal additive manufacturing at the fidelity of the microstructure. The Int. J. of High Perf. Comp. App. (2022) 36: 13-39.